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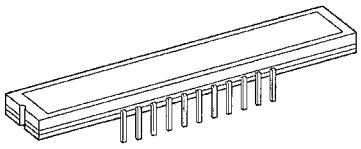
TOSHIBA CCD LINEAR IMAGE SENSOR CCD(Charge Coupled Device)

Preliminary

TCD1205DG

The TCD1205DG is a high sensitive and low dark current 2048−elements linear image sensor. The sensor can be used for POS handscanner.
The device is operated by only 5V power supply, and mounted in 22−pin cerdip package with hermetic sealed optical glass window.
The TCD1205DG has electronic shutter function (ICG).
Electronic shutter function can keep always output voltage constant that vary with the intensity of lights.



WDIP22-G-400-2.54A (A)

Weight: (3.5g (Typ.))

FEATURES

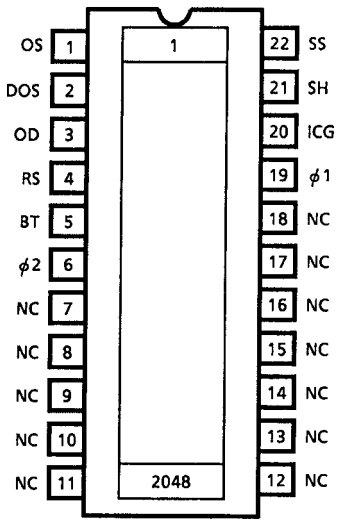
- Number of Image Sensing Elements : 2048
- Image Sensing Element Size : 14μm by 200μm on 14μm centers
- Photo Sensing Region : High sensitive and low dark current pn photodiode
- Clock : 2 phase (5V)
- Internal Circuit : Electronic shutter function (ICG)
- Package : 22 pin cerdip

MAXIMUM RATINGS (Note 1)

CHARACTERISTIC	SYMBOL	RATING	UNIT
Clock Pulse Voltage	V_{φ}	−0.3~8	V
Shift Pulse Voltage	V_{SH}		
Reset, Boost Pulse Voltage	V_{RS}, V_{BT}		
Integration Clear Gate Pulse Voltage	V_{ICG}		
Power Supply Voltage	V_{OD}		
Operating Temperature	T_{opr}	−25~60	°C
Storage Temperature	T_{stg}	−40~100	°C

Note 1: All voltage are with respect to SS terminals (Ground).

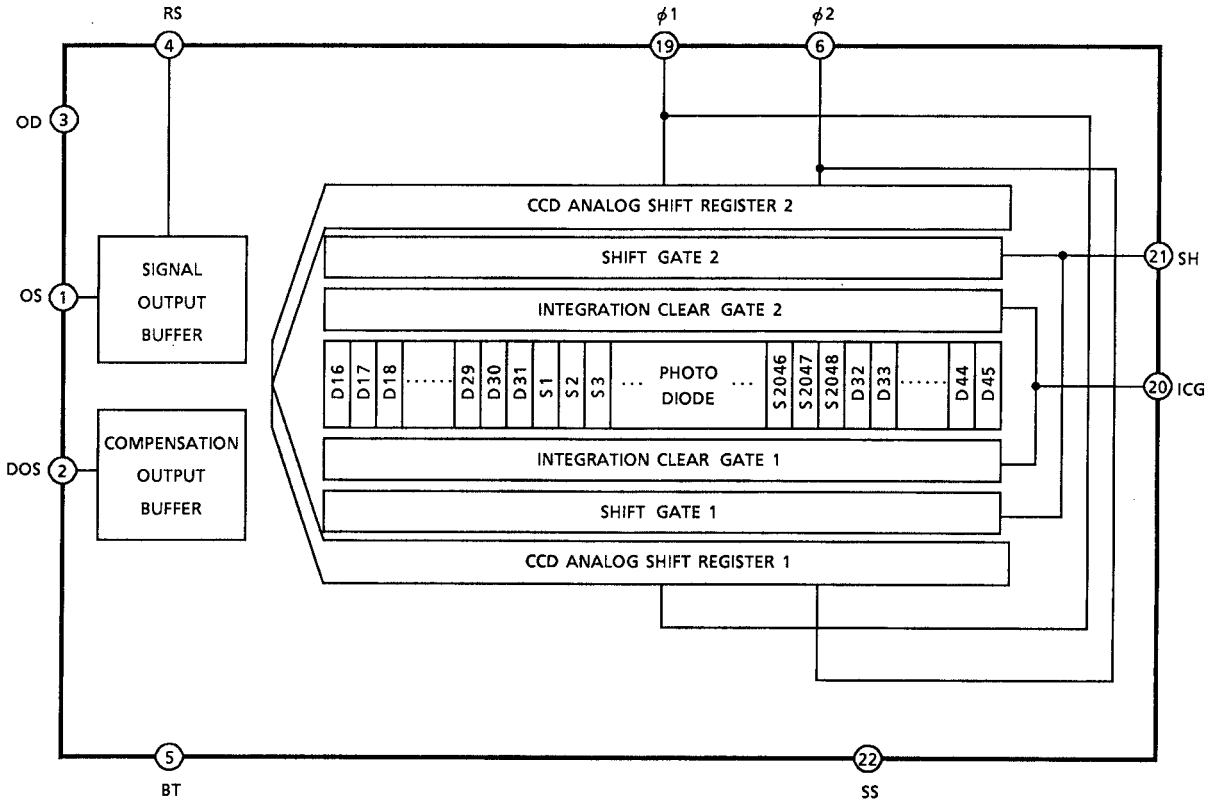
PIN CONNECTION



(TOP VIEW)

000707EBA2

CIRCUIT DIAGRAM



PIN NAMES

$\varphi 1$	Clock (Phase 1)
$\varphi 2$	Clock (Phase 2)
RS	Reset Gate
SH	Shift Gate
I_{CG}	Integration Clear Gate
BT	Boost Gate
OS	Signal Output
DOS	Compensation Output
OD	Power
SS	Ground
NC	Non Connection

OPTICAL / ELECTRICAL CHARACTERISTICS

(Ta = 25°C, V_{OD} = 5V, V_{φ} = V_{SH} = V_{RS} = V_{BT} = 5V (Pulse), f_{φ} = 0.5MHz, f_{RS} = 1MHz, Load Resistance = 100kΩ, t_{INT} (Integration Time) = 10ms, Light Source = Daylight Fluorescent Lamp)

CHARACTERISTIC	SYMBOL	MIN	TYP.	MAX	UNIT	NOTE
Sensitivity	R	64	80	—	V / lx·s	(Note 2)
Photo Response Non Uniformity	PRNU	—	—	10	%	(Note 3)
Saturation Output Voltage	V_{SAT}	0.55	0.8	—	V	(Note 4)
Saturation Exposure	SE	0.006	0.01	—	lx·s	(Note 5)
Dark Signal Voltage	V_{MDK}	—	2	5	mV	(Note 6)
DC Power Dissipation	PD	—	—	25	mW	
Total Transfer Efficiency	TTE	92	95	—	%	
Output Impedance	Z_o	—	0.5	1	kΩ	
Dynamic Range	DR	—	400	—	—	(Note 7)
DC Signal Output Voltage	V_{OS}	1.5	3.0	4.5	V	(Note 8)
DC Compensation Output Voltage	V_{DOS}	1.5	3.0	4.5	V	(Note 8)
DC Mismatch Voltage	$\lvert V_{OS}-V_{DOS}\rvert$	—	—	200	mV	(Note 8)

Note 2: Sensitivity for LED (660nm) is 600V / lx·s (Typ.)

Note 3: Measured at 50% of SE (Typ.)

Definition of PRNU: $PRNU = \frac{\Delta\chi}{\bar{\chi}} \times 100(\%)$

Where $\bar{\chi}$ is average of total signal outputs and $\Delta\chi$ is the maximum deviation from $\bar{\chi}$ under uniform illumination.

Note 4: V_{SAT} is defined as minimum saturation output voltage of all effective pixels.

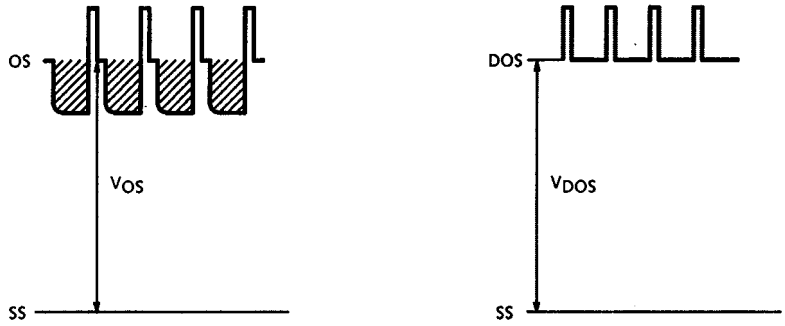
Note 5: Definition of SE : $SE = \frac{V_{SAT}}{R}(lx \cdot s)$

Note 6: V_{MDK} is defined as maximum dark signal voltage of all effective pixels.

Note 7: Definition of DR : $DR = \frac{V_{SAT}}{V_{MDK}}$

V_{MDK} is proportional to t_{INT} (Integration time).
So the shorter t_{INT} condition makes wider DR value.

Note 8: DC signal output voltage and DC compensation output voltage are defined as follows:



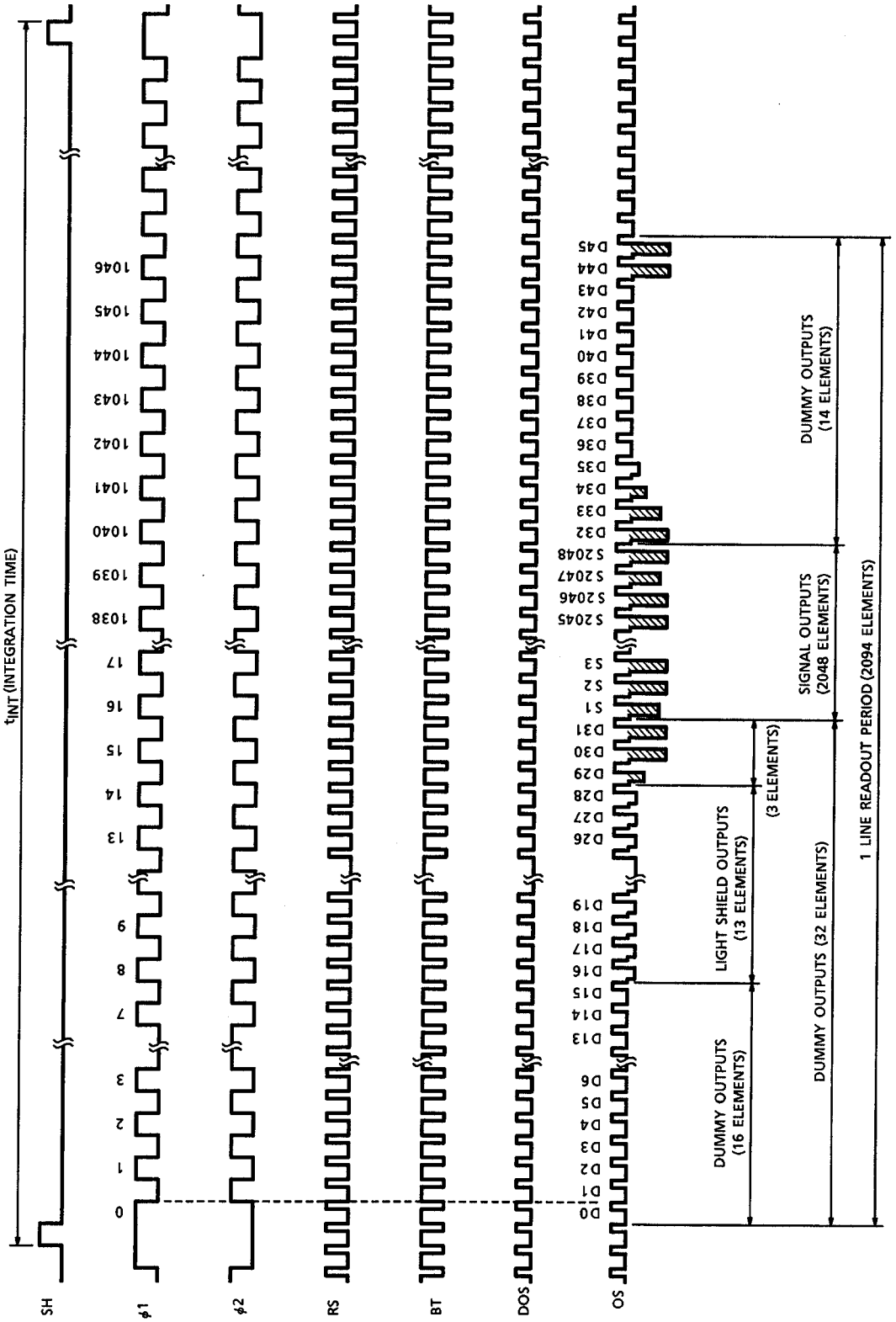
OPERATING CONDITION

CHARACTERISTIC		SYMBOL	MIN	TYP.	MAX	UNIT
Clock Pulse Voltage	"H" Level	V_{φ}	4.5	5.0	5.5	V
	"L" Level		0	0.2	0.5	
Shift Pulse Voltage	"H" Level	V_{SH}	4.5	5.0	5.5	V
	"L" Level		0	0.2	0.5	
Reset, Boost Pulse Voltage	"H" Level	V_{RS}, V_{BT}	4.5	5.0	5.5	V
	"L" Level		0	0.2	0.5	
Integration Clear Gate Voltage	"H" Level	V_{ICG}	4.5	5.0	5.5	V
	"L" Level		0	0.2	0.5	
Power Supply Voltage		V_{OD}	4.5	5.0	5.5	V

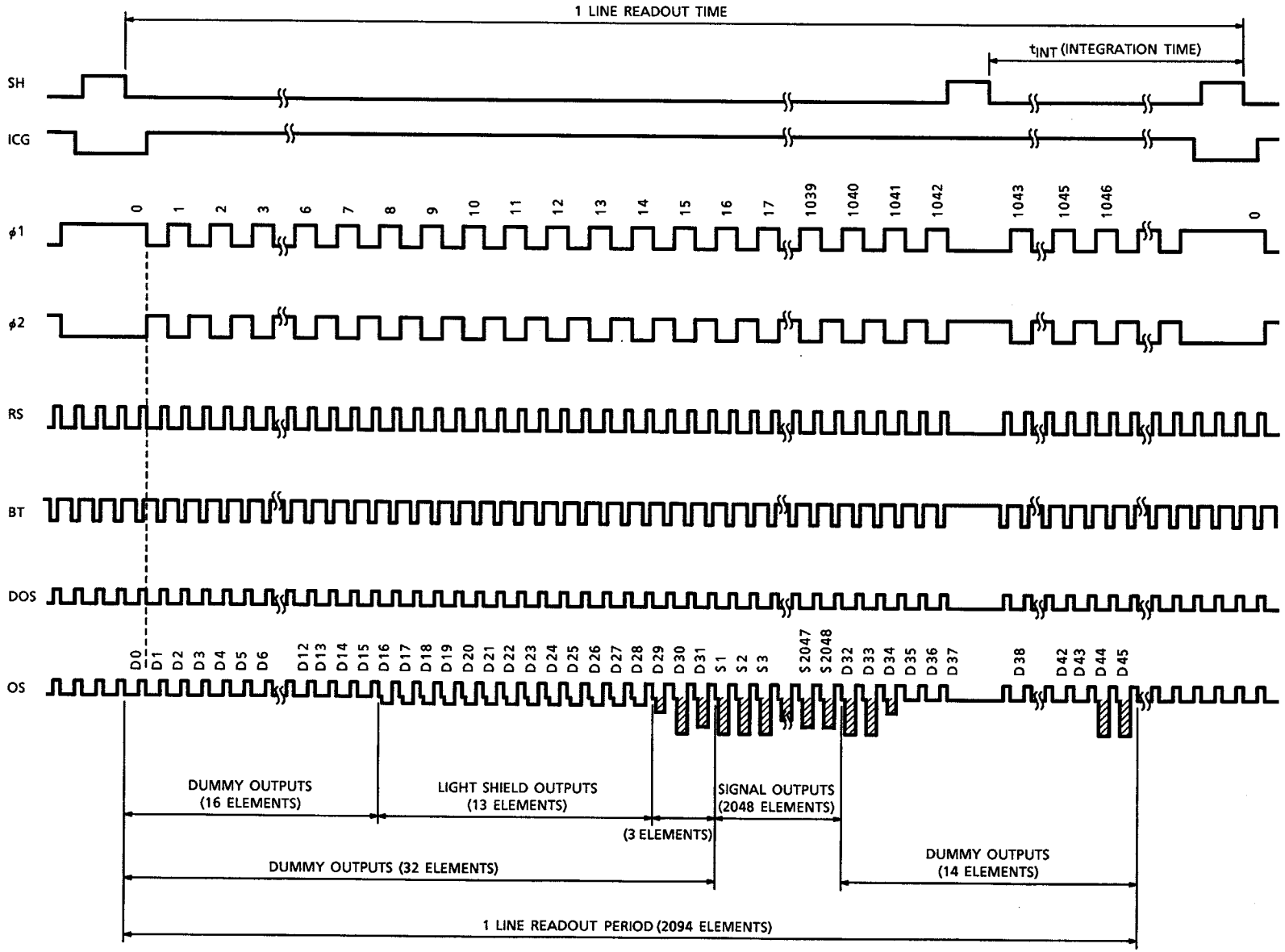
CLOCK CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	MIN	TYP.	MAX	UNIT
Clock Pulse Frequency	f_{φ}	0.01	0.5	1.0	MHz
Reset Pulse Frequency	f_{RS}	0.02	1.0	2.0	MHz
Clock Capacitance	$C_{\Phi A}$	—	400	500	pF
BT Gate Capacitance	C_{BT}	—	10	25	pF
Shift Gate Capacitance	C_{SH}	—	200	250	pF
Reset Gate Capacitance	C_{RS}	—	10	25	pF
Integration Clear Gate Capacitance	C_{ICG}	—	100	200	pF

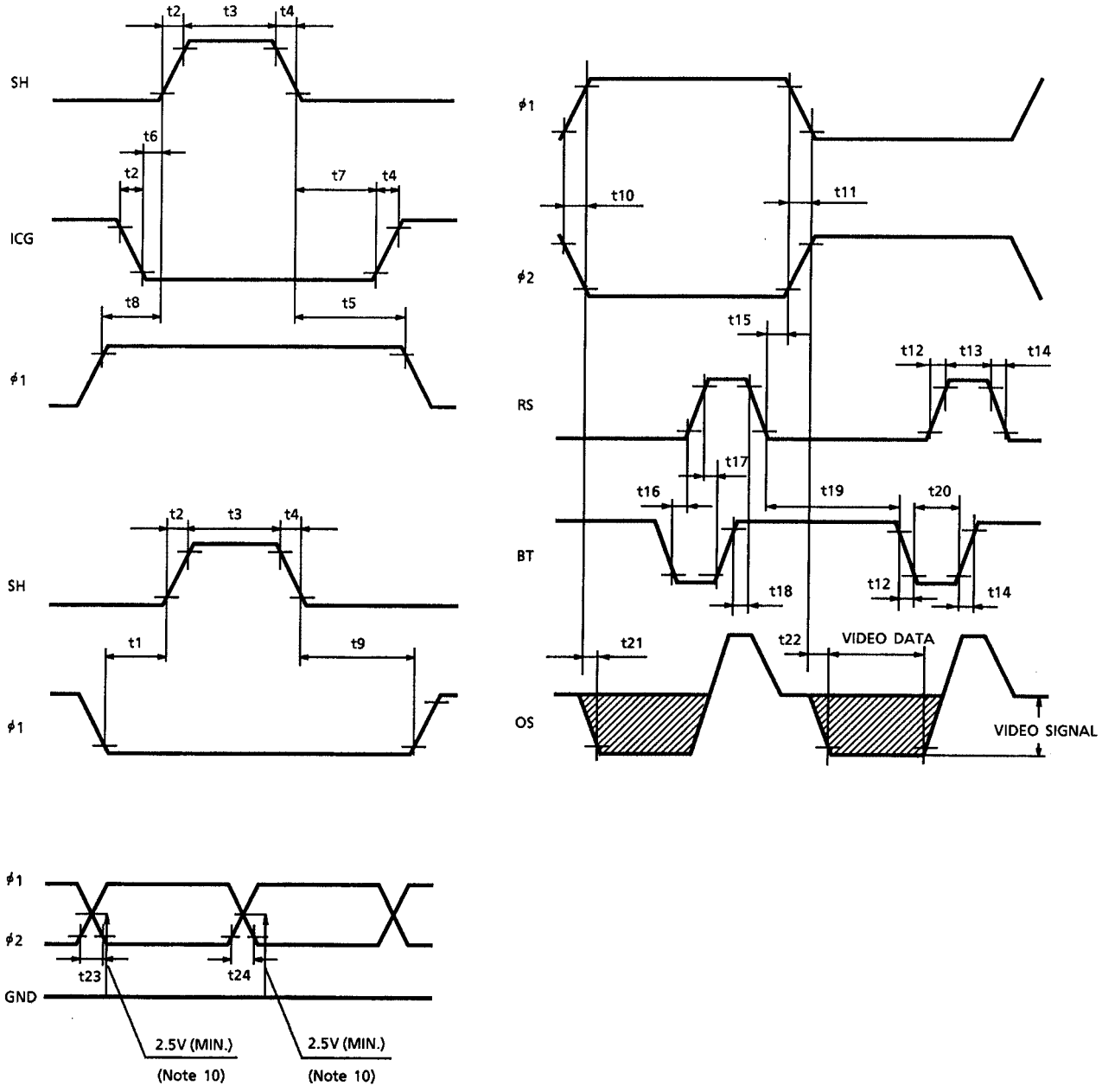
TAIMING CHART



TAIMING CHART (EXAMPLE : USE ELECTRONIC SHUTTER)



TIMING REQUIREMENTS

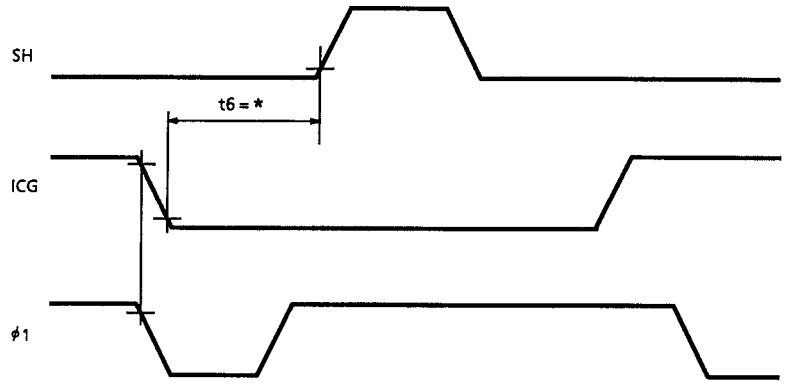


Note 10: If $\varphi 1$ & $\varphi 2$ pulse cross point couldn't be kept over 2.5V, it should be 1.5V and t23 and t24 should be 60ns.

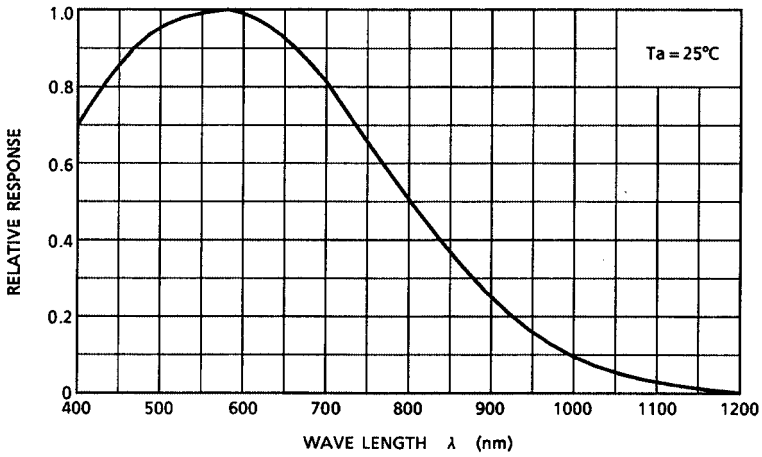
CHARACTERISTIC	SYMBOL	MIN	TYP.	MAX	UNIT
Pulse Timing of SH & φ1	t1	0	100	—	ns
Pulse Timing of SH &φ1	t5	2000	3000	—	ns
SH, ICG Pulse Rise & Fall Time	t2, t4	0	50	—	ns
SH Pulse Width (Note 11)	t3, t3'	1000	2000	—	ns
Pulse Timing of SH & ICG	t6	50	100	*	ns
Pulse Timing of SH & ICG	t7	1000	—	t5	ns
Pulse Timing of ICG &φ1	t8	0	100	—	ns
Pulse Timing of ICG &φ1	t9	500	—	—	ns
φ1, φ2 Pulse Rise & Fall Time	t10, t11	0	60	—	ns
RS, BT Pulse Rise & Fall Time	t12, t14	0	60	—	ns
RS Pulse Width	t13	60	260	—	ns
Pulse Timing ofφ1, φ2, RS	t15	20	—	—	ns
Pulse Timing of RS & BT	t16	50	100	—	ns
Pulse Timing of RS & BT	t17	20	—	—	ns
Pulse Timing of RS & BT	t18	40	—	—	ns
Pulse Timing of RS & BT	t19	200	—	—	ns
BT Pulse Width	t20	70	250	—	ns
Video Data Delay Time	t21, t22	—	80	—	ns

Note 11: Have to use t3 = t3'

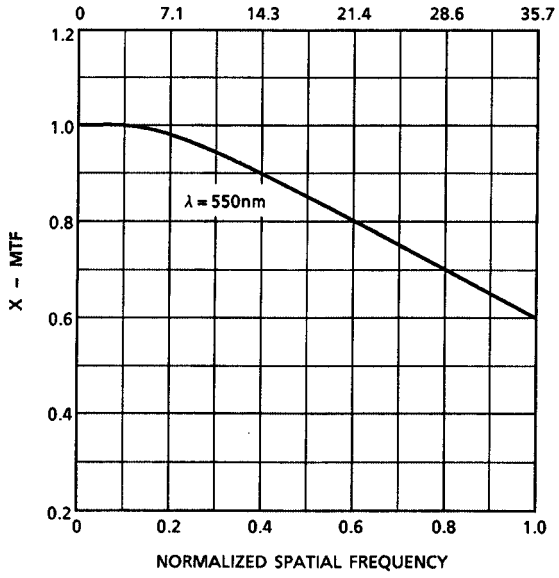
* t6 = MAXIMUM TIMING



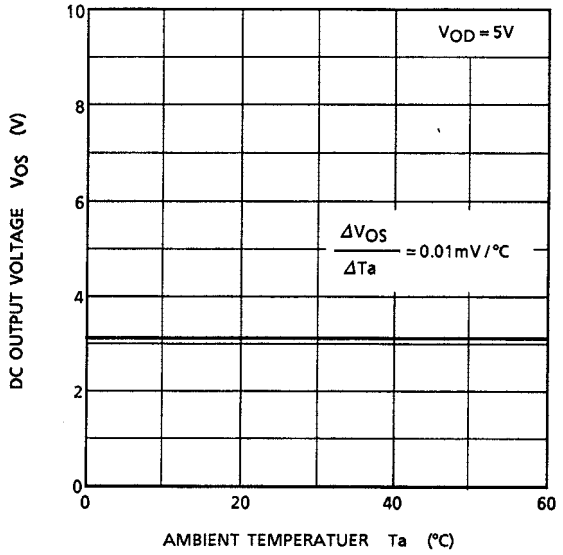
SPECTRAL RESPONSE



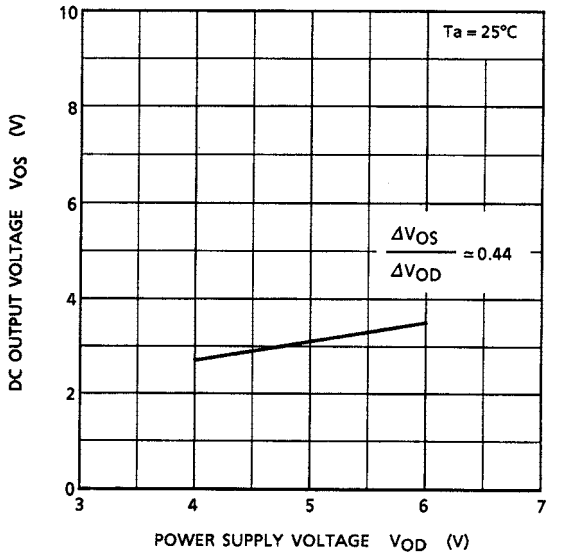
MODULATION TRANSFER FUNCTION
OF X-DIRECTION



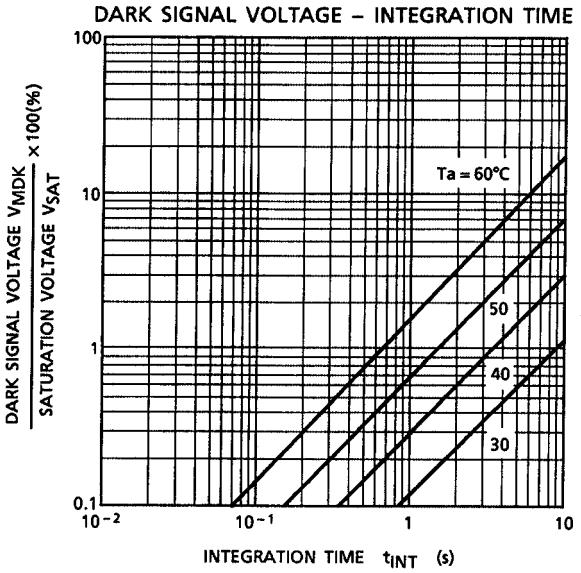
DC OUTPUT VOLTAGE – AMBIENT TEMPERATUER



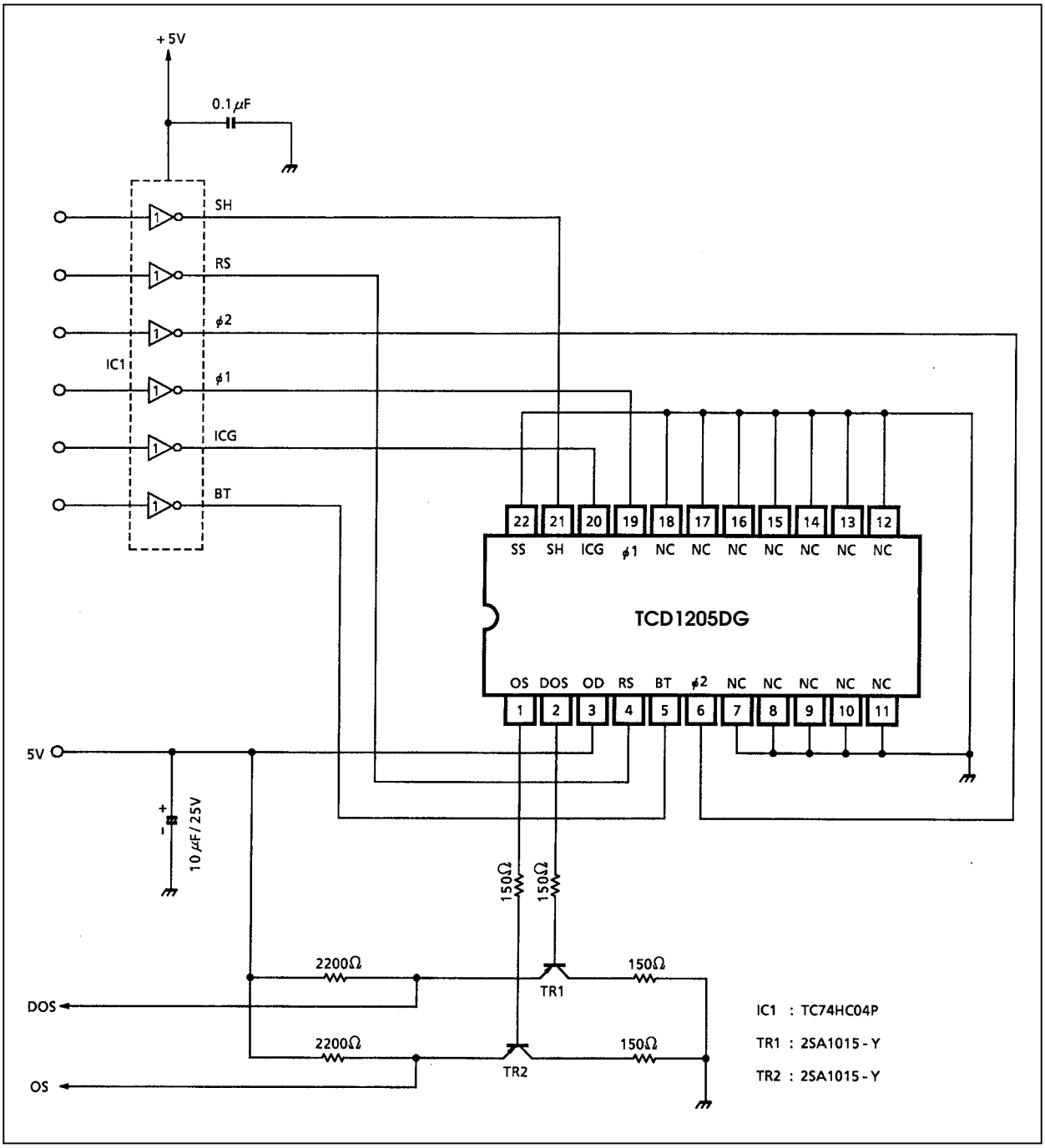
DC OUTPUT VOLTAGE – POWER SUPPLY VOLTAGE



DARK SIGNAL VOLTAGE – INTEGRATION TIME



TYPICAL DRIVE CIRCUIT



CAUTION

1. Window Glass

The dust and stain on the glass window of the package degrade optical performance of CCD sensor.

Keep the glass window clean by saturating a cotton swab in alcohol and lightly wiping the surface, and allow the glass to dry, by blowing with filtered dry N2. Care should be taken to avoid mechanical or thermal shock because the glass window is easily to damage.

2. Electrostatic Breakdown

Store in shorting clip or in conductive foam to avoid electrostatic breakdown.

CCD Image Sensor is protected against static electricity, but interior puncture mode device due to static electricity is sometimes detected. In handing the device, it is necessary to execute the following static electricity preventive measures, in order to prevent the trouble rate increase of the manufacturing system due to static electricity.

a. Prevent the generation of static electricity due to friction by making the work with bare hands or by putting on cotton gloves and non-charging working clothes.
b. Discharge the static electricity by providing earth plate or earth wire on the floor, door or stand of the work room.
c. Ground the tools such as soldering iron, radio cutting pliers of or pincer.

It is not necessarily required to execute all precaution items for static electricity.

It is all right to mitigate the precautions by confirming that the trouble rate within the prescribed range.

3. Incident Light

CCD sensor is sensitive to infrared light. Note that infrared light component degrades resolution and PRNU of CCD sensor.

4. Lead Frame Forming

Since this package is not strong against mechanical stress, you should not reform the lead frame.

We recommend to use a IC-inserter when you assemble to PCB.

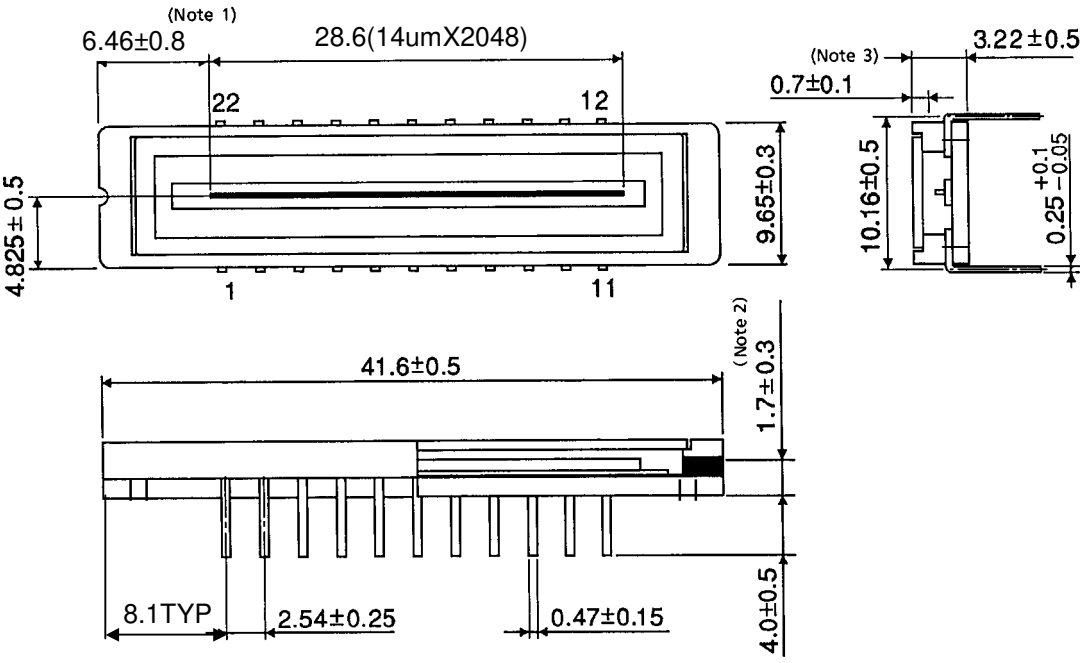
5. Soldering

Soldering by the solder flow method cannot be guaranteed because this method may have deleterious effects on prevention of window glass soiling and heat resistance.

Using a soldering iron, complete soldering within ten seconds for lead temperatures of up to 260°C, or within three seconds for lead temperatures of up to 350°C.

PACKAGE DIEMENSIONS

WDIP22−G−400−2.54A (D) Unit: mm



Note 1: No. 1 SENSOR ELEMENT (S1) TO EDGE OF PACKAGE.
Note 2: TOP OF CHIP TO BOTTOM OF PACKAGE.
Note 3: GLASS THICKNES (n = 1.5)

Weight: (3.5g (Typ.))